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AMENDMENT TO THE CLAIMS

1. (previously presented): A method for fabricating a slider comprising the steps of:

fabricating a plurality of transducers on a wafer;
slicing the wafer into slider bars having a plurality of
sliders formed therealong and fabricating air bearing
surfaces for the plurality of sliders along the slider
bar; and

etching a trench prior to slicing the wafer to form a
trailing edge of the air bearing surfaces of the
plurality of sliders.

2. (currently amended): The method of claim 1 and further comprising the step of:

depositing an overcoat layer prior to slicing the wafer and
forming the trench in the overcoat layer.

3. (original): The method of claim 1 wherein the air bearing
surfaces of the plurality of sliders along the slider bar are
formed using a photoalignment masking process.

4. (previously presented): The method of claim 1 wherein a
recessed surface of the trench forms the trailing edge for the
raised bearing surfaces of the sliders.

5. (original): The method of claim 1 and further comprising
the step of:

planarizing the slider or wafer prior to etching the trench.

6. (original): A method for fabricating a slider comprising
the step of:

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fabricating a trench having a recessed trench surface spaced from a trailing end surface of the slider to form a trailing edge of a raised bearing surface of the slider defined by an etched depth of the trench of the slider.

7. (original): The method of claim 6 wherein the trench is fabricated at a wafer level prior to slicing the wafer into slider bars to form a plurality of sliders therealong.

8. (original): The method of claim 7 and further comprising the step of:

forming air bearing surfaces on the slider bar after slicing the slider bar from the wafer.

9. (original) A head comprising:

a slider having a transducer portion fabricated proximate a trailing end of the slider; and

a trench in an overcoat layer of the transducer portion forming a trailing edge of the slider and the trailing edge having a recessed dimension relative to a trailing end surface of the slider defined by an etched depth of the trench of the slider.

10. (cancelled)

11. (original): The head of claim 9 wherein the transducer portion includes inductive and/or magnetoresistive transducer elements.

12. (original): The head of claim 9 wherein the trench forms a trailing edge of a raised bearing surface of the slider.

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13. (currently amended): The method of claim 6 wherein the trench is fabricated in ~~one~~a first process step and comprising the step of:

fabricating a raised bearing surface and a recessed bearing surface on a disc facing surface of the slider in ~~another~~second process step and the raised bearing surface in the ~~other~~second process step having a trailing edge defined by the trench fabricated in the ~~one~~first process step.

14. (currently amended): The method of claim 13 and further comprising the step of:

planarizing or lapping the disc facing surface of the slider in addition to the ~~one~~first process step and the ~~other~~second process step.

15. (currently amended): The method of claim 14 and further comprising the step of planarizing or lapping the disc facing surface of the slider prior to the ~~other~~second process step and after the ~~one~~first process step.

16. (currently amended): The method of claim 13 wherein the raised bearing surface and the recessed bearing surface are formed using a photoalignment masking process in the ~~other~~second process step.

17. (currently amended): The method of claim 13 wherein the trench is etched in the ~~one~~first process step prior to forming the raised bearing surface and the recessed bearing surface in the ~~other~~second process step.

18. (currently amended): The method of claim 13 wherein the raised bearing surface and the recessed bearing surface and the

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trailing edge of the raised bearing surface are etched relative to different orthogonal surfaces of the slider in the ~~enefirst~~ and the ~~ethersecond~~ process steps.

19. (currently amended): The method of claim 13 and further comprising:

etching the trench relative to a first orientation in the ~~enefirst~~ process step; and

etching the recessed bearing surface relative to a second orientation in the ~~ethersecond~~ process step.

20. (previously presented): A slider formed from the method of claim 6.

21. (previously presented): A slider formed from the method of claim 1.